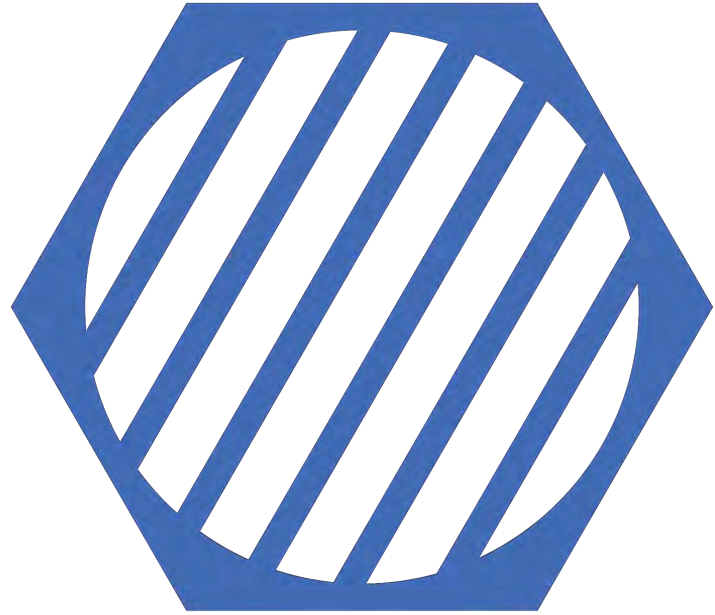




**SIXLINE**  
SEMICONDUCTOR



# SIXLINE

SEMICONDUCTOR

Founded Sept. 2022  
UW-Madison Spinout

Overcomes 30-year challenge to leverage aligned carbon nanotubes for *faster performance, lower cost* radiofrequency devices, with possibility to expand into broader semiconductor device markets

**Semiconductors are  
the basis of all  
modern electronics**

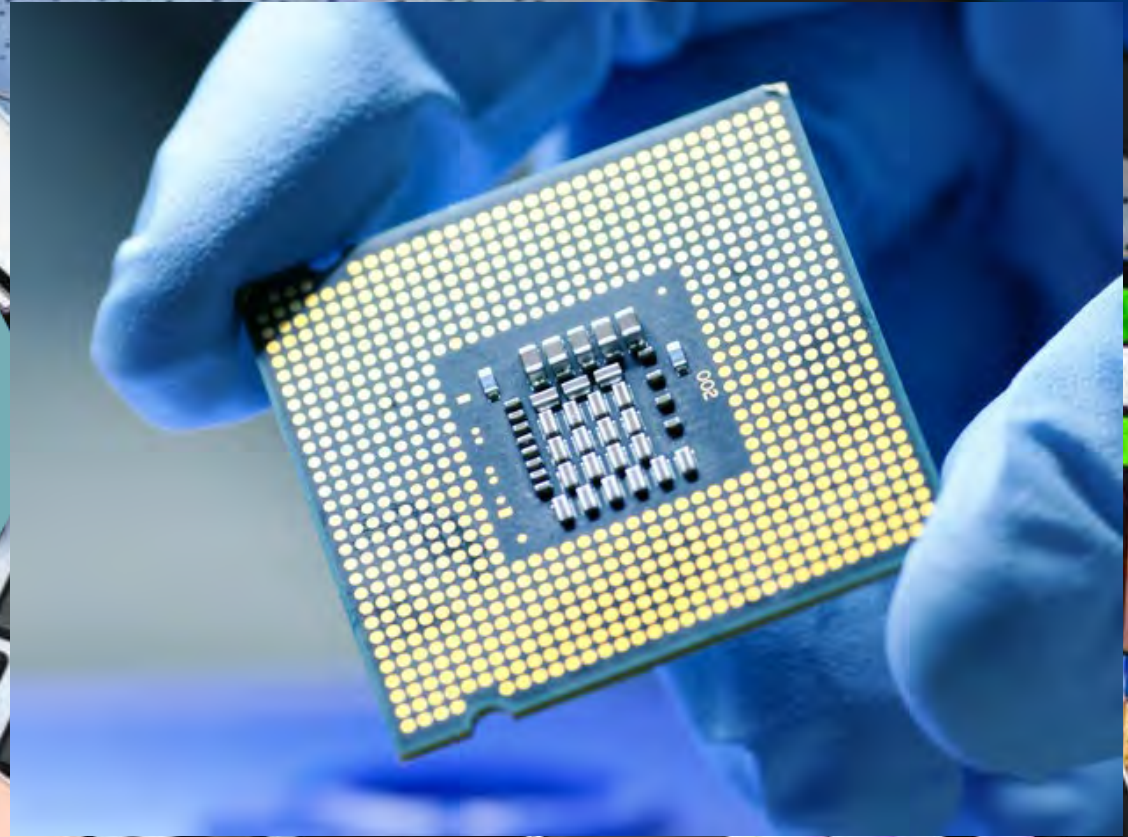
***Current materials  
cannot meet  
demands of next-gen  
devices***

3D ICs

6G/7G

Sensors

Flexible  
devices



Scalable,  
cost-effective  
approach  
to *outperform current  
materials* and drive the  
next revolution in  
electronics

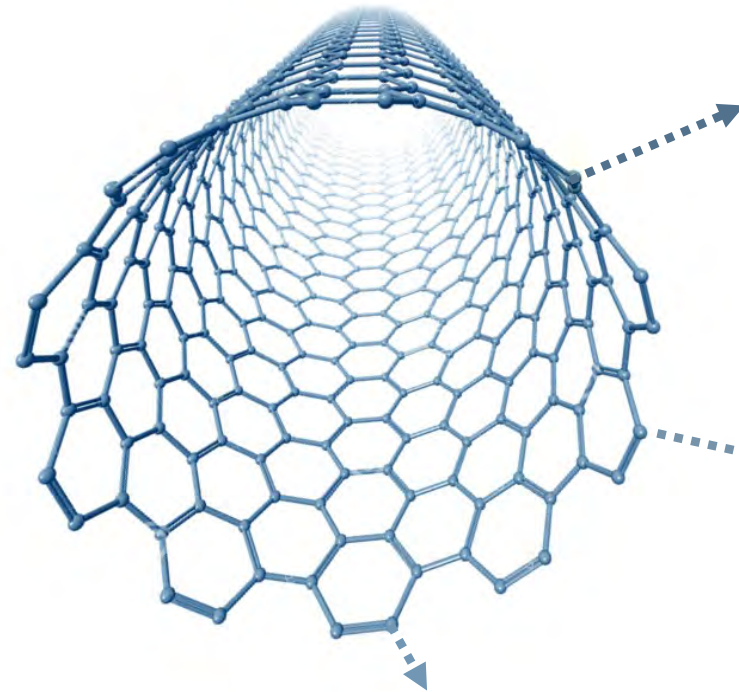




# The Superior Performance of Carbon Nanotubes

Cost-effective solutions

Layer of carbon atoms rolled into a cylinder



## SixLine's 1<sup>st</sup> Target Radiofrequency (RF)

- 3-8x higher frequencies than current materials
- On-chip integration with Si
- Larger data bandwidths
- Intrinsic linearity

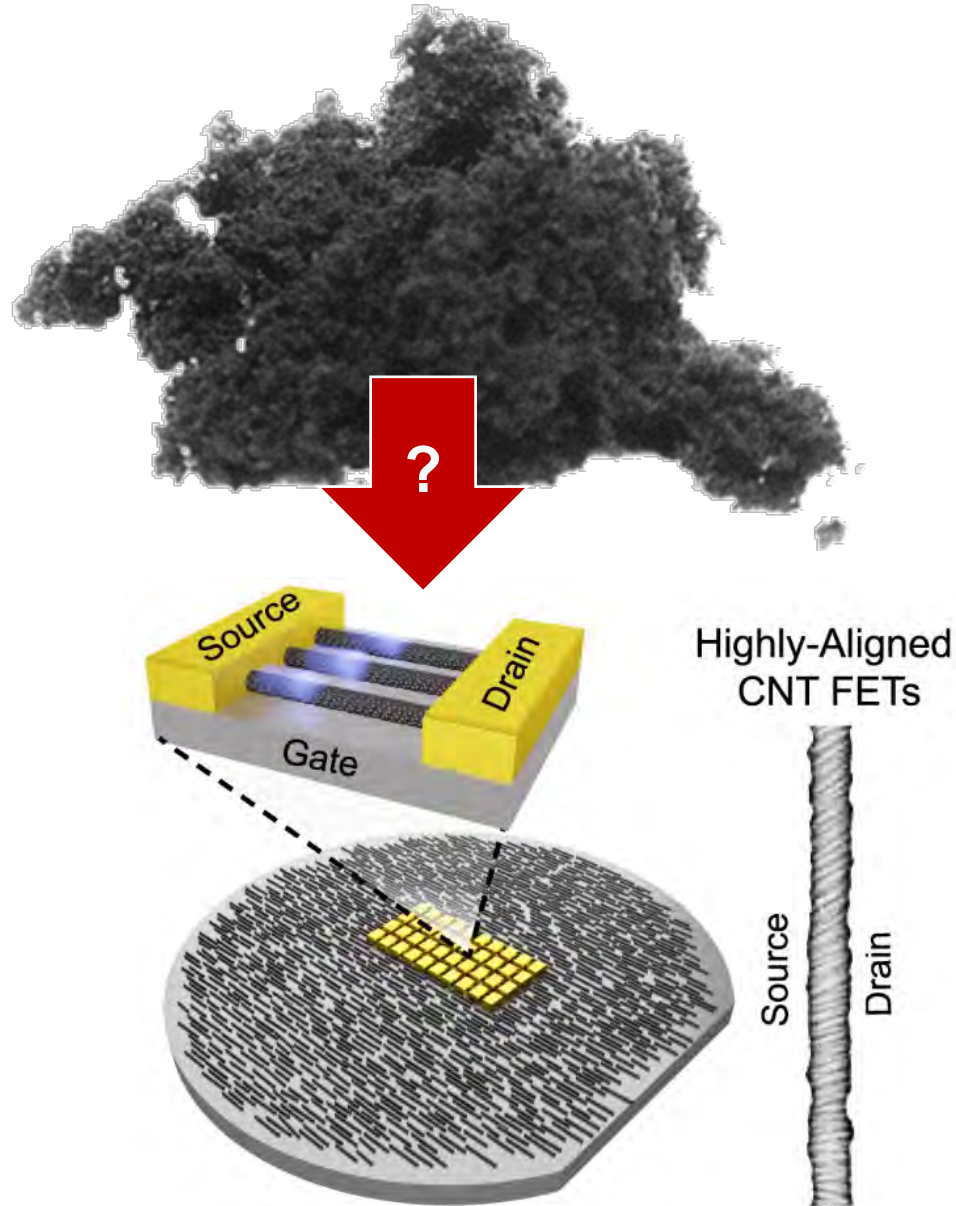
## Logic

- 100 - 1000x lower power consumption
- Enables 3D circuits—route to advance Moore's Law

## Thin-Film Electronics

- 10-100x faster performance
- Mechanically resilient

# Nanotube Obstacles

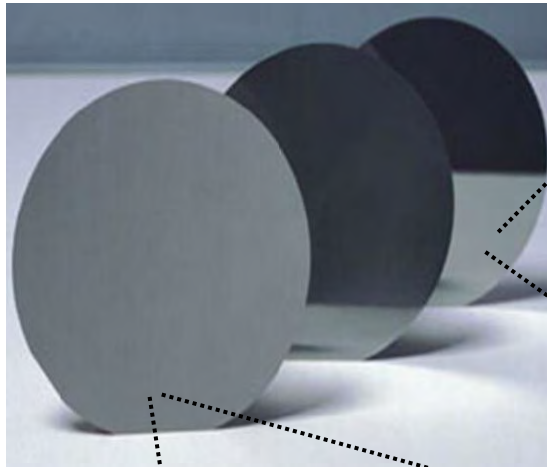


30-year challenge: translating random nanotube soot into highly-aligned semiconducting carbon nanotube arrays from a commercial and scalable process for high-performance electronics

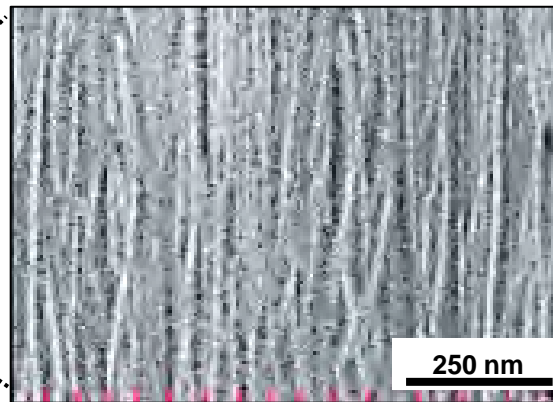
# SixLine Produces Ideally Aligned Electronics-Grade Nanotubes

Highly-aligned, registered arrays of semiconducting nanotubes from a fast, easily scalable process

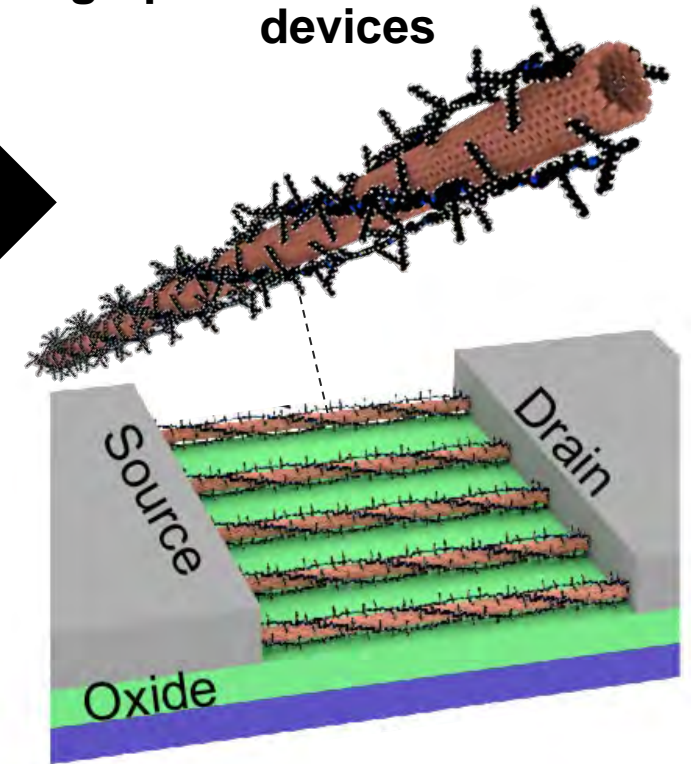
Industry scalable



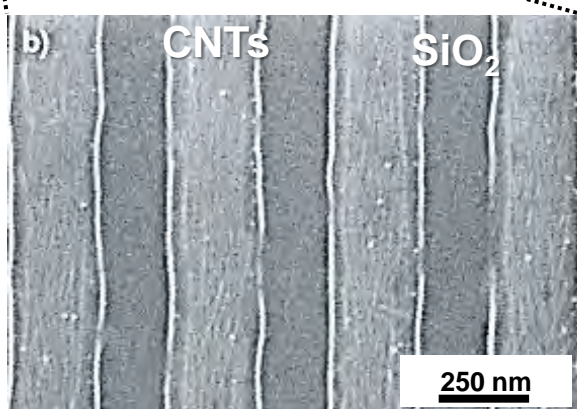
Highly aligned ( $\pm 7^\circ$ )



High-performance electronic devices



Registered Placement



- ✓ Compatible with conventional fabrication techniques
- ✓ Fast process—high info turns
- ✓ Manageable byproducts

Process occurs at room-temperature/pressure—enables system-on-a-chip integration

# Strong Performance and Cost Advantages

## PROPRIETARY PROCESS CONTROL

Targeted Packing Density

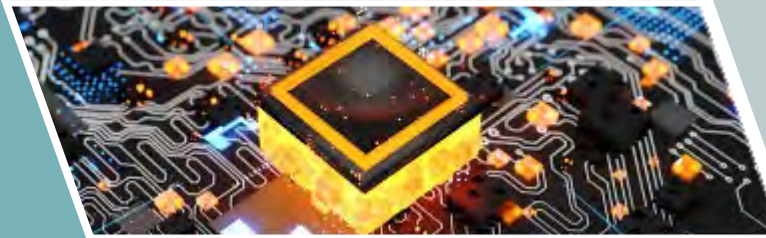
Room Temperature Process

High Alignment

Uniform Films

Selected Placement

## APPLICATIONS



## COMPETITIVE ADVANTAGES FOR RF

### Next-gen RF: 6G/7G, Advanced WiFi

- >3x frequency performance
- High data fidelity at high freq
- System-on-a-chip integration

### 30 – 60% Lower Cost vs GaAs

- >50% lower wafer cost
- 250% more fab facilities
- 55% lower die cost
- 65% throughput increase



# Technology Traction

- 8 years of research
- \$2M in research funding—significant progress
- Uniform alignment across 4” wafer demonstrated
- State-of-the-art RF device performance via previous industrial partner
- Strong industry engagement
- 10 patents (8 issued, 2 filed)
  - Process and composition of matter protection

Strong position in research area, comprehensive patent protection, capable founders, and experienced research team

# SixLine's Technology has Large Potential Value Across Multiple Markets

## RF Wafer Market

**\$2.1B**

CAGR of 8.8%

***SixLine's 1<sup>st</sup> Target Total Market***

## Logic Wafer Market

**\$11.3B**

CAGR of 3.6%

## Semiconductor Fabrication Equipment Market

**\$119B**

CAGR of 8%

## Application Markets

### **RF Components**

**\$15B**

CAGR of 16%

### **Biosensors**

**\$24.9B**

CAGR of 8%

# Experienced Team

**Prof. Mike Arnold, PhD**

*Chief Technical Advisor, Co-founder, Co-inventor*



**Jeff Moore**

*Strategy/Commercial Support*



**Katy Jinkins, PhD**

*CEO, Co-founder, Co-inventor*



[katy@sixlinesemi.com](mailto:katy@sixlinesemi.com)

**Dominick Bindl, PhD**

*Technical/Commercial Advisor*



**Prof. Padma Gopalan, PhD**

*Technical Advisor, Co-inventor*



Significant amount of materials, industry, and startup expertise



# SIXLINE

SEMICONDUCTOR

**Produces nanotube materials/arrays enabling next-gen electronic performance**

- Significant performance and cost advantages
- Comprehensive IP library
- Strong industry engagement
- Overcomes 30-year challenge to leverage aligned carbon
- Current market focus: RF
- Will expand into other semiconductor markets